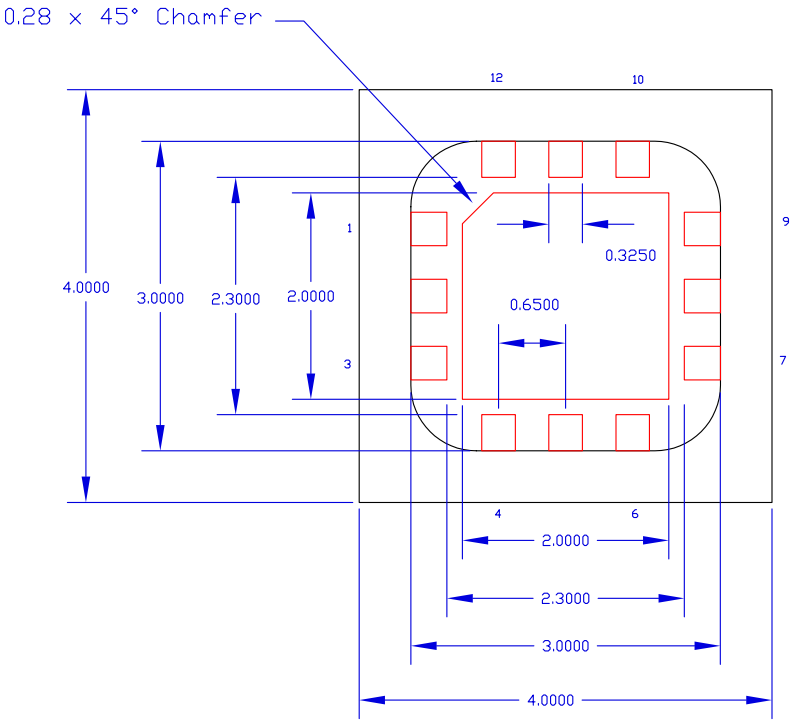
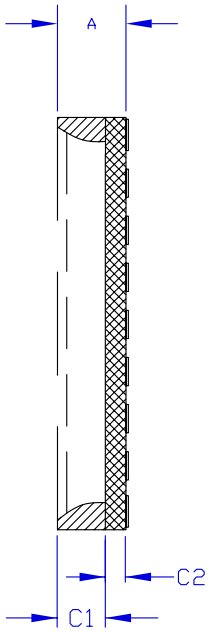
| REV | DESCRIPTION | DATE | APPROVAL |
|---|---|---|---|

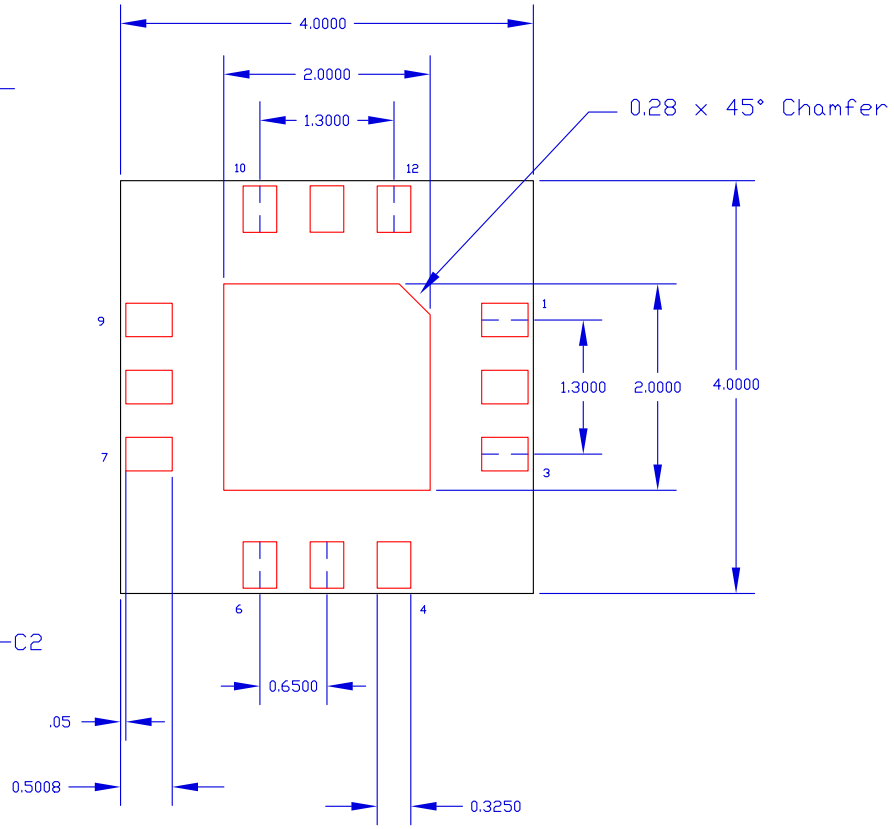
## TOP VIEW

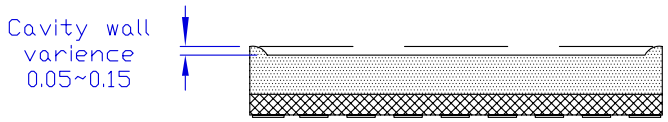



## SIDE VIEW




## BOTTOM VIEW




## SIDE VIEW

Note:

1. Organic substrate
2. Cavity Dam: Hysol FP4451TD
3. Pads: Cu/Ni/Au
4. Copper Thickness: 12μm~18μm (0.5~0.7mil)
5. Bonding Pad Gold Thickness: 1.3μm (50 micro-inch)
6. PCB Pads Gold Thickness: 0.13μm (5 micro-inch)
7. Nickel Thickness: 3.8μm (150 micro-inch)
8. All Dimensions Are mm

| HEIGHT TABLE | | | |
|---|---|---|---|
| SERIES | C1 | C2 | A |
| A-QFN | 0.63 | 0.27 | 0.90 |
| A-TQFN | 0.38 | 0.27 | 0.65 |
| TOL +/- | +/- 0.10 | +/- 0.05 | +/- 0.15 |

OTHER SIZES AVAILABLE

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| TOLERANCES UNLESS NOTED: | |
|---|---|
| X.XX | ± |
| X.XXX | ± |
| X.XXXX | ± |
| ANGLES | ± |

ALL DIMENSIONS ARE IN: ☐ INCHES ☐ MILLIMETERS

THIRD ANGLE PROJECTION:

| APPROVALS | DATE |
|---|---|
| DRAWN TA | 11/29/08 |
| ENG | |
| MFG | |
| QA | |
| CUST | |
| REVISED | |

Mirror Semiconductor ™

TITLE 12-LEAD 4MM P=0.65MM A-QFN (AIR) OPEN CAVITY

| SCALE | SIZE | DRAWING NO. | REV |
|---|---|---|---|
| NONE | A | 461210 | A |

DO NOT SCALE DRAWING

SHEET 1 OF 1